EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE USING THEREOF

ABSTRACT OF THE DISCLOSURE

According to the present invention, there is provided an epoxy resin composition for packaging the semiconductor element, obtained by formulating: (A) an epoxy resin; (B) a phenolic resin; (C) a curing accelerator; (D) an inorganic filler; and (E) an oxidized polyethylene wax having a drop point within a range of from 60 to 140 degree C, an acid value within a range of from 10 to 100 (mg KOH/g), a number average molecular weight within a range of from 500 to 20,000, and a mean particle size within a range of from 5 to 100 μm, wherein at least one of (A) epoxy resin and (B) phenolic resin is a novolac structured resin having biphenylene structure, and wherein content of (E) oxidized polyethylene wax in epoxy resin composition is within a range of from 0.01 to 1 % wt.

Figure 1 accompanies the abstract.